Escess Mail No. EV528708699US

Attorney Docket No. 108298705US Disclosure No. 02-1607.00/US

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Form PTO-1449 (Modified) (Use several sheets if necessary)

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of

COMPLETE IF KNOWN		
Application Number	10/665,219	
Confirmation Number	6284	
Filing Date	September 17, 2003	
First Named Inventor	Whonchee Lee	
Group Art Unit	3723	
Examiner Name	Dung V. Nguyen	
Attorney Docket No.	108298705US	

U.S. PATENT DOCUMENTS					
·	Pages, Columns, Lines, Where				
Examiner Initials*	Cite No.	Kind Co NUMBER (if know		tor Filing Date of Cited Document	Relevant Passages or Relevant Figures Appear
WV¢	4	5,624,300~	Kishii et al.	04/29/1997	
		6,689,258 B	Lansford et al.	02/10/2004	
		6;776,693 / B	Duboust et al.	08/17/2004	

EXAMINER	DATE CONSIDERED
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DVN	**	U.S. Application No. 09/651,779 (Atty. Docket No. 10829,8515US)		Moore	Filed 08/30/2000	
	**	U.S. Application No. 09/651,808		Chopra et al.	Filed 08/30/2000	. "
	**	U.S. Application No. 09/653,392 /		Chopra et al.	Filed 08/31/2000	
	**	U.S. Application No. 09/653,411 /		Lee et al.	Filed 08/31/2000	
	••	U.S. Application No. 10/230,463 / (Atty. Docket No. 10829.8672US)		Lee et al.	Filed 08/29/2002	
	••	U.S. Application No. 10/230,602 (Atty. Docket No. 10829.8674US)		Chopra	Filed 08/29/2002	
	**	U.S. Application No. 10/230,628/ (Atty. Docket No. 10829.8673US)		Lee et al.	Filed 08/29/2002	
		2001/0025976/	A1	Lee	10/04/2001	
		2001/0036746	A1	Sato et al.	11/01/2001	
		2002/0025763	A1	Lee et al.	02/28/2002	
		2002/0025760/	A1	Lee et al.	02/28/2002	
		2002/0025759~	A1	Lee et al.	02/28/2002	
		2002/0052126	A1	Lee et al.	05/02/2002	
		2002/0070126	A1	Sato et al.	06/13/2002	
		2003/0054729	A1	Lee et al.	03/20/2003	
-		2003/0109198	A1	Lee et al.	06/12/2003	

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DVV	140.	2003/0129927/	A1	Lee et al.	07/10/2003	
1		2003/0226764	A1	Moore et al.	12/11/2003	
		2,315,695~		Faust	04/06/1943	
		2,516,105,		der Mateosian	07/25/1950	
		3,334,210/		Williams et al.	08/01/1967	
1		4,839,005 >		Katsumoto et al.	06/13/1989	
		5,244,534~		Yu et al.	09/14/1993	
1		5,300,155~	1	Sandhu et al.	04/05/1994	
		5,344,539 /		Shinogi et al.	09/06/1994	
1		5,567,300 ~		Datta et al.	10/22/1996	
1		5,575,885		Hirabayashi et al.	11/19/1996	
		5,618,381~		Doan et al.	04/08/1997	
		5,676,587 ~		Landers et al.	10/14/1997	
		5,681,423/		Sandhu et al.	10/28/1997	
		5,780,358 ~		Zhou et al.	07/14/1998	
1		5,807,165/		Uzoh et al.	09/15/1998	
		5,840,629 ~		Carpio	11/24/1998	
		5,846,398 /		Carpio	12/08/1998	
1		5,863,307 /		Zhou et al.	01/26/1999	
		5,897,375		Watts et al.	04/27/1999	
1		5,911,619/		Uzoh et al.	06/15/1999	
		5,930,699/		Bhatia	07/27/1999	
1		5,934,980		Koos et al.	08/10/1999	

6

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NVG		5,952,687	Kawakubo et al.	09/14/1999	
		5,954,975~	Cadien et al.	09/21/1999	
		5,954,997	Kaufman et al.	09/21/1999	
1		5,972,792 /	Hudson	10/26/1999	
		5,993,637/	Hisamatsu et al.	11/30/1999	
		6,001,730/	Farkas et al.	12/14/1999	
		6,010,964~	Glass	01/04/2000	
		6,024,856 -	Haydu et al.	02/15/2000	
		6,033,953/	Aoki et al.	03/07/2000	
		6,039,633,	Chopra	03/21/2000	
		6,046,099	Cadien et al.	04/04/2000	
		6,051,496~	Jang	04/18/2000	
		6,060,386 /	Givens	05/09/2000	
		6,060,395 /	Skrovan et al.	05/09/2000	
		6,063,306/	Kaufman et al.	05/16/2000	
		6,066,030 ~	Uzoh	05/23/2000	
		6,066,559/	Gonzalez et al.	05/23/2000	
		6,068,787	Grumbine et al.	05/30/2000	
		6,083,840 /	Mravic et al.	07/04/2000	
		6,100,197/	Hasegawa	08/08/2000	
		6,103,096,	Datta et al.	08/15/2000	
		6,103,628/	Talieh	08/15/2000	
V		6,115,233 /	Seliskar et al.	09/05/2000	

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DV~	,,,,	6,117,781/		Lukanc et al.	09/12/2000	
		6,121,152		Adams et al.	09/19/2000	
		6,132,586/		Adams et al.	10/17/2000	
		6,143,155/		Adams et al.	11/07/2000	
		6,171,467/	B1	Weihs et al.	01/09/2001	
		6,174,425	B1	Simpson et al.	01/16/2001	
		6,176,992/	B1	Talieh	01/23/2001	
		6,180,947/	B1	Stickel et al.	01/30/2001	
		6,187,651/	B1	Oh	02/13/2001	
		6,196,899/	B1	Chopra et al.	03/06/2001	
		6,197,182/	B1	Kaufman et al.	03/06/2001	
		6,206,756~	B1	Chopra et al.	03/27/2001	
		6,218,309/	B1	Miller et al.	04/17/2001	
,		6,250,994/	B1	Chopra et al.	06/26/2001	
		6,259,128/	B1	Adler et al.	07/10/2001	
		6,273,786 -	B1	Chopra et al.	08/14/2001	
		6,276,996/	B1	Chopra	08/21/2001	
		6,280,581/	B1	Cheng	08/28/2001	
		6,287,974/	B1	Miller	09/11/2001	
		6,299,741/	B1	Sun et al.	10/09/2001	
	 	6,303,956/	B1	Sandhu et al.	10/16/2001	
	1-1-	6,313,038	B1	Chopra et al.	11/06/2001	
 		6,328,632/	B1	Chopra	12/11/2001	
 	 	6,368,190/	B1	Easter et al.	04/09/2002	

6

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DVW			6,379,223	B1	Sun et al.	04/30/2002		
DVN			6,455,370	B1	Lane	09/24/2002		
				FOR	EIGN PATENT DOCUMENTS			
Examiner	Cite	Office	Foreign Patent or Application	Kind Cod		Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	7
DVN	**	JP	2001077117/	A2, A3		03/23/2001		
1	**	EP/	0459397	A1	Kabushiki Kaisha Toshiba	12/04/1991		
	**	wo	02/064314	A1	Speedfam-IPEC Corporation	08/22/2002		
	**	wo/	00/26443	A2, A3	Nutool, Inc.	05/11/2000		
	**	wo	00/28586	A2, A3	Micron Technology, Inc.	05/18/2000		
	**	wo-	00/32356	A1	Nutool, Inc.	06/08/2000		
	••	wo	00/59008	A2, A3	Nutool, Inc	10/05/2000		
1	**	wo	00/59682	A1	Nutool, Inc	10/12/2000		
		1	OTHER PR	OR ART	-NON PATENT LITERATURE	OCUMENTS		
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book manazine lournal serial symposium catalog stc.), date page(s), volume issue number(s), publisher, city			7			
₩.	***	ABOAF, J.A. and R.W. BROADIE, IBM Technical Disclosure Bulletin, Rounding of Square-Shape Holes in Silicon Wafers, Vol. 19, No. 8, p. 3042, January 1977, XP-002235690, NN 77013042.						
	**	ATMI, Inc., adapted from a presentation at the Semicon West '99 Low Dielectric Materials Technology Conference, San Francisco, California, July 12, 1999, pp. 13-25.						
	**	BASSOUS, E., IBM Technical Disclosure Bulletin, Low Temperature Methods for Rounding Silicon Nozzles, Vol. 20, No. 2, July 1977, pp. 810-811, XP-002235692, NN 7707810.						
	••	BERNHARDT, A.F., CONTOLINI, R.J., MAYER, S.T, "Electrochemical Planarization for Multi-Level Metallization of Microcircuitry," <i>CircuiTree Journal</i> , Vol. 8, No. 10, pp. 38, 40, 42, 44, 46, and 48, Oct. 1995.						

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≯ √√	**	D'HEURLE, F.M. and K.C. PARK, IBM Technical Disclosure Bulletin, Electrolytic Process for Metal Pattern Generation, Vol. 17, No. 1, pp. 271-272, June 1974, XP-002235691, NN 7406271.			
	4+	FRANKENTHAL, R.P. and EATON, D.H., "Electroetching of Platinum in the Titanium-Platinum-Gold Metallization on Silicon Integrated Circuits", <i>Journal of The Electrochemical Society</i> , Vol. 123, No. 5, pp. 703-706, May 1976.			
	**	HUANG, C.S. et al., "A Novel UV Baking Process to Improve DUV Photoresist Hardness," pp. 135-138, Proceedings of the 1999 International Symposium on VLSI Technology, Systems, and Applications: Proceedings of Technical Papers: June 8-10, 1999, Taipei, Taiwan, Institute of Electrical and Electronics Engineers, Inc., September 1999.			
	**	JUCHNIEWICZ, R. et al. "Influence of Pulsed Current of Platinised Titanium and Tantalum Anode Durability," International Congress on Metallic Corrosion, Proceedings - Volume 3, pp. 449-453, Toronto, June 3-7, 1984.			
	**	KONDO, S. et al., "Abrasive-Free Polishing for Copper Damascene Interconnection," Journal of the Electrochemical Society, Vol. 147, No. 10, pp. 3907-3913, The Electrochemical Society, Inc., Pennington, New Jersey, 2000.			
	••	McGraw-Hill, Concise Encyclopedia of Science & Technology, Sybil P. Parker, Editor in Chief, Fourth Edition, p. 367, McGraw-Hill, New York, 1998.			
	**	Micro Photonics, Inc., "CSM Nano Hardness Tester," 6.pages, retrieved from the Internet on July 29, 2002, http://www.microphotonics.com/nht.html >.			
	**	Micro Photonics, Inc., CSM Application Bulletin, "Low-load Micro Scratch Tester (MST) for characterisation of thin polymer films," 3 pages, retrived from the Internet on July 25, 2002, http://www.microphotonics.com/mstABpoly.html >. http://www.microphotonics.com/mstABpoly.html >.			
	••	PhysicsWorld, "Hard Materials", excerpt of "Superhard Superlattices," 1 page, January 1998, S. Barnett and A. Madan, retrieved from the Internet on July 29, 2002, http://physicsweb.org/box/world/11/1/11/world-11-1-1-1			

6

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